IN THE SPECIFICATION

Page 1, below the title, change "Harald Bottner" to --Haraold Böttner--;

Page 1, paragraph [0001], change as follows:

[0001] The invention relates to a solder for joining microelectromechanical components, to a microelectronical and/or microelectromechanical component formed using this solder, to a microelectromechanical device formed using this solder, and to a process for producing a component or device using this solder.

Page 10, paragraph [0055], change as follows:

[0055] The thicknesses of the two materials (gold, bismuth) are in the range between a few hundred nm and 10 μm, preferably around 1-2 μm. The materials used for the auxiliary process engineering layers for etching or lift-off depend, in terms of their nature and layer thickness, on the requirements of the soldering materials and on the patterning technology employed. Gold and bismuth and standard physical coating processes can preferably be used for the two soldering partners, and photoresist, e.g. as sacrificial layers, can preferably be used for the lift-off process.